

ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration
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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class* Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information								
Company Name *	Company Unique ID	Unique ID Authority	Response Date*					
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sat, Feb 22, 2014 03:27 AM					
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *					
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Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *					
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com					

Requester Item Number	Mfr Ite	m Number	Mfr Item Name		Effective Date	Version	N	Manufacturing Site	Weight*	UOM	Unit Type
KA78L05AIMTF	KA78L	05AIMTF	SOT-89				SUB	CONTRACTOR	0.050916	g	Each
Manufacturing Process Information											
Terminal Finish	Base Alloy	J-STD-02	J-STD-020 MSL Rating		Peak Process Body Temperature		Max Time at Peak Temperature		No Ret	No Reflow cycles	
Matte Tin (Sn)	CU Alloy		1	260 C			30 seconds			3	

^{*} Required Field

RoHS Material Composition Declaration

Declaration Type * Custom

RoHS Directive 2011/65/EU **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration *

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance * Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

None

Declaration Signature

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

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Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name SOT-89

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.469	Supplier		Silicon	0.469	7440-21-3	9211
Die Attach	Other Organic Materials	0.089	Supplier		Acrylic Resin	0.022	54208-63-8	436
			Supplier		Silver	0.067	7440-22-4	1310
Encapsulation	Thermoplastics	26.116	В	Antimony/Antimony Compounds	Antimony Trioxide	0.653	1309-64-4	12825
			В	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	0.783	6386-73-8	15378
			Supplier		Carbon Black	0.261	1333-86-4	5129
			Supplier		Epoxy Resin	3.780	29690-82-2	74241
			Supplier		Silica, vitreous	20.639	60676-86-0	405355
Lead Frame	Copper & its alloys	23.745	Supplier		Copper	23.600	7440-50-8	463513
			Supplier		Iron	0.024	7439-89-6	465
			Supplier		Phosphorus	0.007	7723-14-0	140
			Supplier		Silver	0.114	7440-22-4	2239
Plating	Other Nonferrous metals & alloys	0.472	Supplier		Tin	0.472	7440-31-5	9270
Wire Bond	Precious metals	0.025	Supplier		Gold	0.025	7440-57-5	487